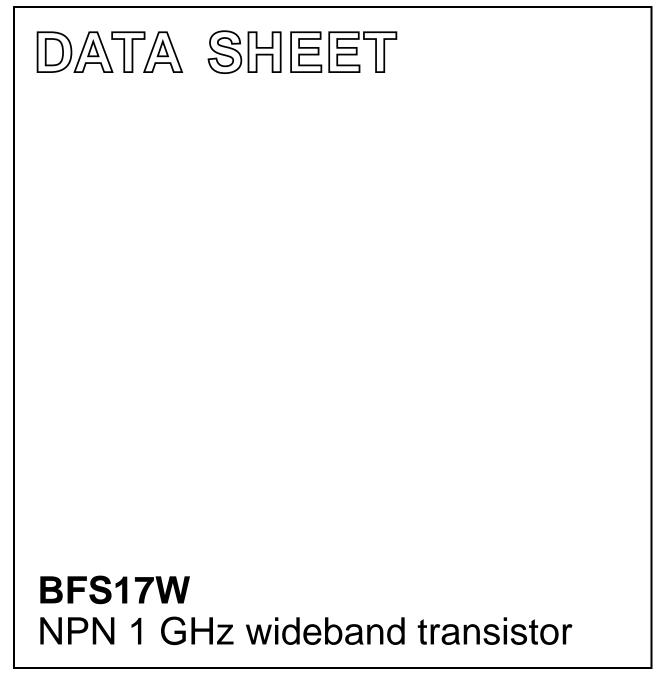
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of November 1992 1995 Sep 04



BFS17W

APPLICATIONS

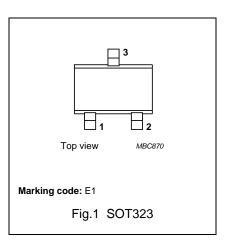
PINNING

Primarily intended as a mixer, oscillator and IF amplifier in UHF and VHF tuners.

DESCRIPTION

Silicon NPN transistor in a plastic SOT323 (S-mini) package. The BFS17W uses the same crystal as the SOT23 version, BFS17.

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage		-	_	25	V
V _{CEO}	collector-emitter voltage		-	-	15	V
I _C	DC collector current		-	_	50	mA
P _{tot}	total power dissipation	up to $T_s = 118 \text{ °C}$; note 1	-	_	300	mW
h _{FE}	DC current gain	I _C = 2 mA; V _{CE} = 1 V	25	90	-	
f _T	transition frequency	$I_{C} = 25 \text{ mA}; V_{CE} = 5 \text{ V}$	-	1.6	-	GHz
C _c	collector capacitance	I _E = 0; V _{CB} = 10 V; f = 1 MHz	-	0.8	1.5	pF
C _{re}	feedback capacitance	I _C = 1 mA; V _{CE} = 5 V; f = 1 MHz	-	0.75	-	pF
Tj	junction temperature		-	-	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	-	25	V
V _{CEO}	collector-emitter voltage	open base	-	15	V
V _{EBO}	emitter-base voltage	open collector	-	2.5	V
I _C	collector current (DC)		-	50	mA
P _{tot}	total power dissipation	T _s = 118 °C; note 1	-	300	mW
T _{stg}	storage temperature		-65	+150	°C
Т _ј	junction temperature		-	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	up to $T_s = 118 \text{ °C}$; note 1	190	K/W

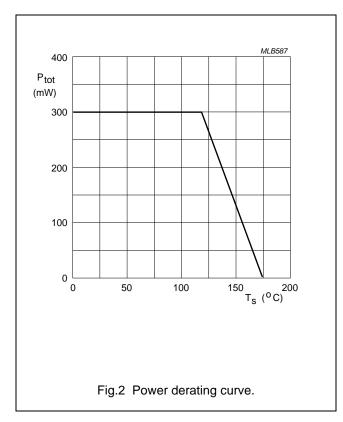
Note

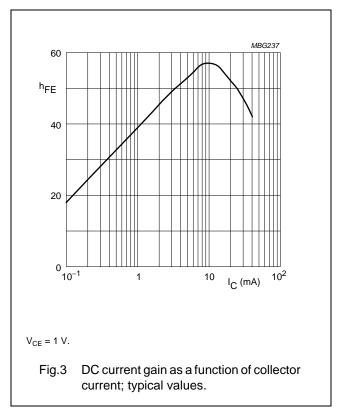
1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

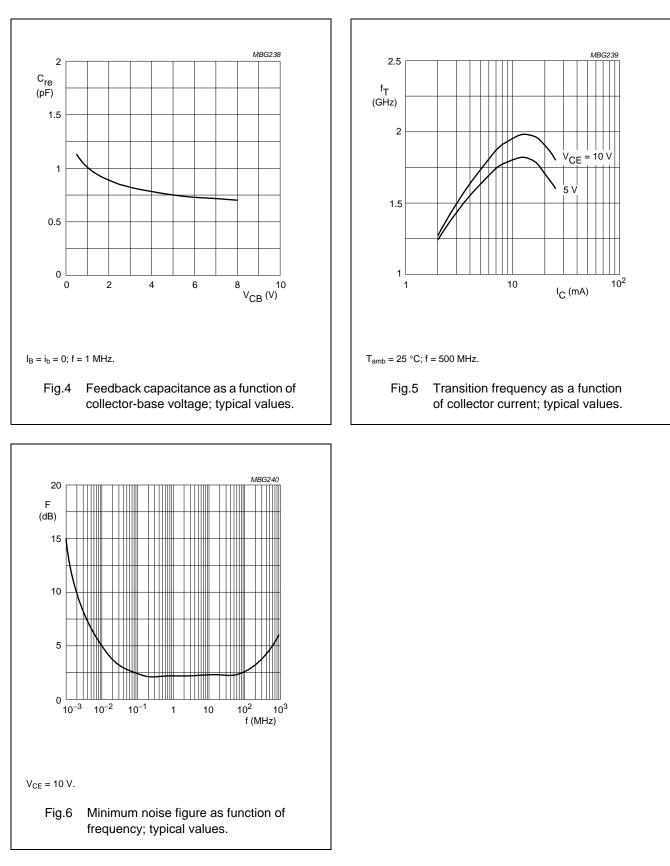
 $T_i = 25 \ ^{\circ}C$ (unless otherwise specified).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = 10 V	_	-	10	nA
h _{FE}	DC current gain	I _C = 2 mA; V _{CE} = 1 V	25	90	-	
f _T	transition frequency	I _C = 25 mA; V _{CE} = 5 V; f = 500 MHz	-	1.6	-	GHz
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V;$ f = 1 MHz	-	0.8	1.5	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V;$ f = 1 MHz	-	2	-	pF
C _{re}	feedback capacitance	$I_B = i_b = 0; V_{CE} = 5 V;$ f = 1 MHz; T _{amb} = 25 °C	-	0.75	-	pF
F	noise figure	$I_{C} = 2 \text{ mA}; V_{CE} = 5 \text{ V};$ f = 500 MHz; $\Gamma_{S} = \Gamma_{opt}$	-	4.5	-	dB





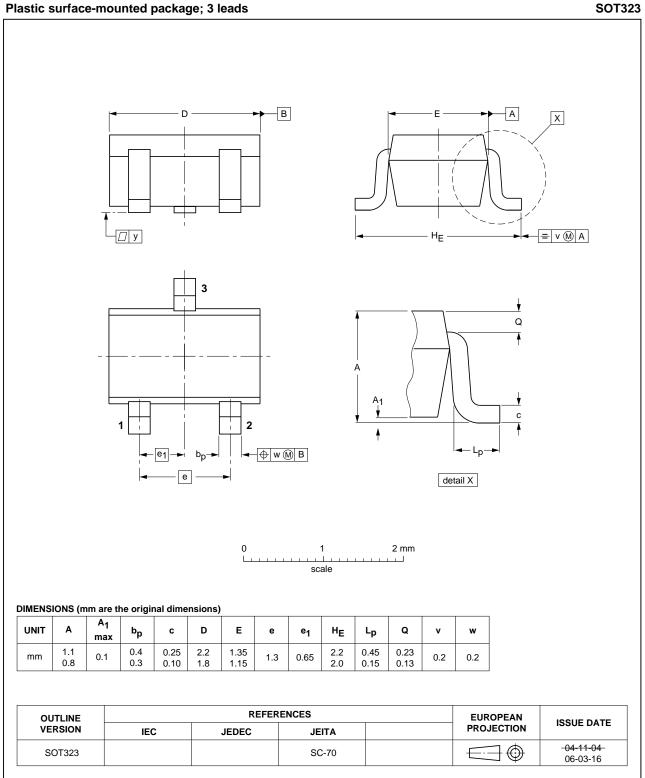
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BFS17W

NPN 1 GHz wideband transistor

PACKAGE OUTLINE



BFS17W

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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BFS17W

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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